DLA Land and Maritime - VQ
Supplemental Information Sheet for Electronic QML-31032

Specification Details: **Date: 8/15/2017**

Specification: MIL-PRF-31032
Title: Printed Circuit Board/Printed Wiring Board
Federal Supply Class (FSC): 5998
Conventional: No
Specification contains quality assurance program: Yes
MIL-STD-790 Established Reliability & High Reliability: No
MIL-STD-690 Failure Rate Sampling Plans & Procedures: No
Weibull Graded: Yes
Specification contains space level reliability requirements: No
Specification allows test optimization: Yes

Contact Information:

Office of Primary Involvement: Electronic Devices Branch, DLA Land and Maritime - VQE
Primary Qualifying Activity Contact: 614-692-0627, e-mail: vqe.ls@dla.mil
Secondary Qualifying Activity Contact: 614-692-0625, e-mail: vqe.rp@dla.mil

Notes:

If a manufacturer desires to have test data considered for qualification, it must be certified and meet all qualification test requirements of MIL-PRF-31032 and the applicable associated specification.

The listing of printed board manufacturing lines in the QML applies only to printed boards produced in the plant(s) specified herein. Therefore, only those printed boards that have been manufactured and tested on the certified/qualified lines listed herein can be supplied as QML printed boards.

The DLA Land and Maritime - VQE contacts for QML companies can be located in the file "31032 main points-of-contact" at website:
http://www.dscc.dla.mil/offices/sourcing and qualification/offices.asp?section=VQE

QML is a definition of a manufacturer's verified capabilities. Manufacturers may use the add-on qualification process to qualify capabilities that are not currently listed on the QML. The user is encouraged to contact the manufacturer or Qualifying Activity to make arrangements for QML availability.

The following abbreviations are used in this listing:

Ag: Silver
Au: Gold
CAGE: Commercial and Government Entity (Code)
Cu: Copper
ENIG: Electroless Nickel Immersion Gold
HASL: Hot Air Solder Level
ImmAg: Immersion Silver
IR: Infrared
LPI: Liquid Photoimageable
MIX: Mix of SMT and THM
Ni: Nickel
OSP: Organic Surface Protection
Pb: Lead
Pd: Palladium
PTH: Plated Thru Hole
SMOBC: Solder Mask Over Bare Copper
SMT: Surface-Mount Technology
Sn: Tin
THM: Through-Hole Mounting

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: **Compunetics Inc.** 700 Seco Rd, Monroeville, PA, 15146 US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 30598 Phone: 412-858-1272 Fax: EMail: sales@compunetics.com

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
Qualification Letters: VQ(VQE-13-026082), VQ(VQE-15-029422)
Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
Max. Panel Size: 18" x 24"
Max. Number of Layers: 32
Max. Board Thickness: .26"
Min. Hole Size: .0098" Drilled Plated-Through Hole Before Plating
Aspect Ratio: 10.8:1 Through-Hole
Min. Conductor Width/Space: .004"/.004"
Hole Preparation: Plasma Desmear, Plasma Etchback
Hole Wall Conductive Coating: Electroless Copper
Copper Plating: Periodic Reverse Plate
Hole Fill/Via Plug: Conductive, Non-Conductive
Solder Resist: Liquid Photoimageable
Finish System: ENIG, HASL
Additional Fab Capabilities: Foil Lamination
Controlled Impedance: Differential, Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
Qualification Letters: VQE-15-029722
Composition: M - Mixed based material printed boards
Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant; Woven Glass Reinforced, Hydrocarbon Resin with Ceramic Fill
Max. Panel Size: 18" x 24"
Max. Number of Layers: 18
Max. Board Thickness: .177"
Min. Hole Size: .017" Drilled Plated-Through Hole Before Plating
Aspect Ratio: 10.4:1 Through-Hole
Min. Conductor Width/Space: .0047"/.006"
Hole Preparation: Plasma Desmear
Copper Plating: Periodic Reverse Plate
Solder Resist: Liquid Photoimageable
Finish System: ENIG, HASL
Additional Fab Capabilities: Blind Vias, Sequential Lamination
Controlled Impedance: Differential, Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/3, MIL-PRF-31032/4
Qualification Letters: VQ (VQE-17-031349)
Flex Base Material: Copper Clad Adhesiveless Polyimide
Max. Panel Size: 24" x 18"
Max. Number of Layers: 4
Max. Board Thickness: .024"
Min. Hole Size: .018" Drilled Plated-Through Hole Before Plating
Aspect Ratio: 1.3 Through-Hole
Min. Conductor Width/Space: .004"/.004"
Hole Preparation: Plasma Desmear
Hole Wall Conductive Coating: Electroless Copper
Copper Plating: Periodic Reverse Plate
Finish System: HASL
Flex Usage: Use A (Flex During Installation)